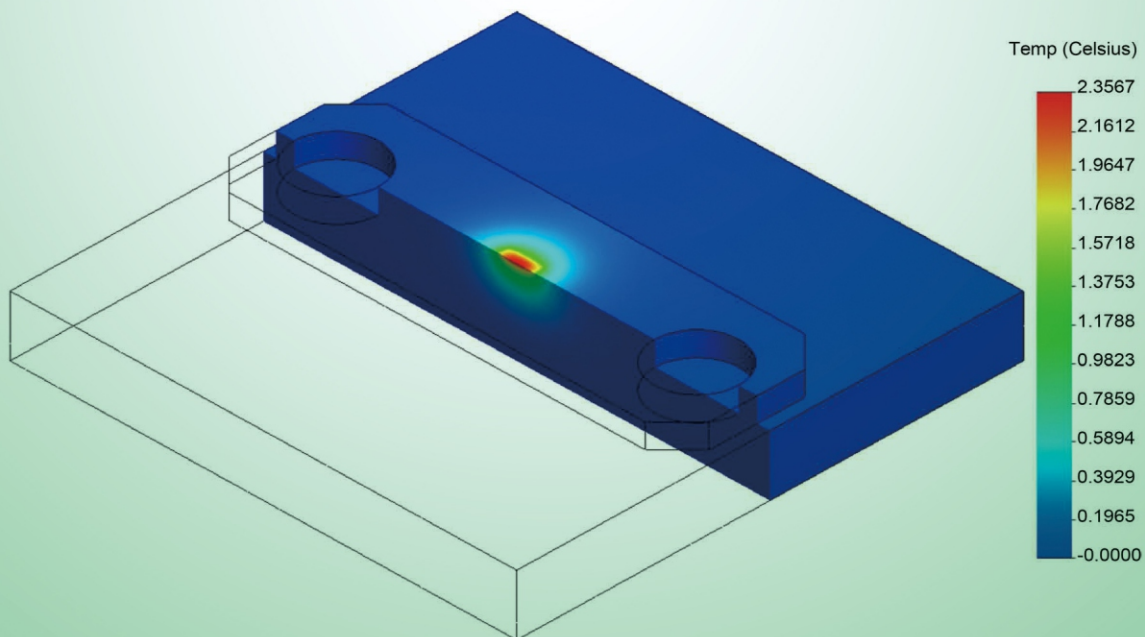


Journal of Electronics Cooling and Thermal Control



ISSN: 2162-6162



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ISSN 2162-6162 (print) ISSN 2162-6170 (online)

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Journal of Electronics Cooling and Thermal Control (JECTC)

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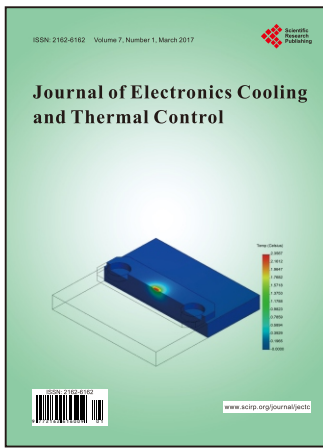
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Journal of Electronics Cooling and Thermal Control

ISSN 2162-6162 (print) ISSN 2162-6170 (online)
<http://www.scirp.org/journal/jectc>

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- Fan design and performance
- Forced convection heat transfer
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- Phase changing heat transfer
- Phonon
- Radiation
- Spray cooling
- Temperature stability
- Thermal modeling of electronics systems and components

Technologies based on these transport processes such as

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